



PRODUCT DATA SHEET



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Datasheet

ces Sami

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Low Capacitance Series TVS

Features

- Low operating voltage: 5V
- Low capacitance
- Solid-state silicon-avalanche and active circuit triggering technology
- Back-drive protection for power-down mode
- Lead-free version available



SOT-23-6L

IEC Compatibility (EN61000-4)

- IEC 61000-4-2 (ESD) ±25kV (air), ±20kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4.5A (8/20µs)

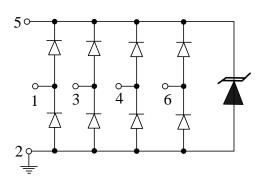
Mechanical Characteristics

- SOT-23-6L package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS Compliant

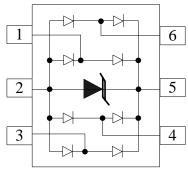
Applications

- Video/Graphics Card
- Digital Visual Interface (DVI)
- USB2.0 Power and Data lines protection
- Notebook and PC Computers
- Monitors and Flat Panel Displays

Circuit Diagram



Schematic & PIN Configuration



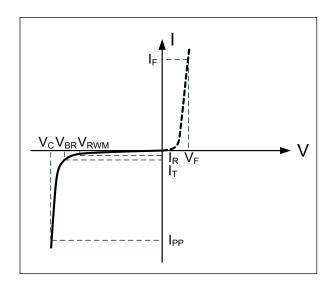
SOT-23-6L (Top View)



Absolute Maximum Rating					
Rating	Symbol	Value	Units		
Peak Pulse Power (t _p =8/20μs)	P _{PP}	90	Watts		
Peak Pulse Current (t _p =8/20µs)	I _{pp}	4.5	А		
Operating Temperature	TJ	-55 to +150	°C		
Storage Temperature	Tstg	-55 to +125	°C		

Electrical Parameters (T=25°C)

Symbol	Parameter
I PP	Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
VRWM	Working Peak Reverse Voltage
lR	Reverse Leakage Current @ VRWM
V _{BR}	Breakdown Voltage @ I⊤
lτ	Test Current
lF	Forward Current
VF	Forward Voltage @ I _F



Electrical Characteristics

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin5 to pin2 T=25°C			5.0	٧
Reverse Breakdown Voltage	V_{BR}	I⊤=1mA Pin 5 to pin2	5.6			٧
Reverse Leakage Current	I _R	V _{RWM} =5V, T=25°C Pin 5 to pin2			500	nA
Forward Voltage	VF	I⊤=15mA		0.8	1.5	V
Clamping Voltage	Vc	I _{PP} =4.5A, t _P =8/20μs I/O pin to GND			20	V
		V _R = 0V, f = 1MHz I/O pin to GND		2.5	3.5	pF
Junction Capacitance	C _j	V _R = 0V, f = 1MHz Between I/O pins		1.0	2.0	pF



Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

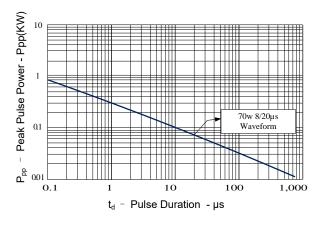


Figure 2: Power Derating Curve

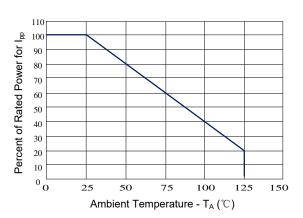


Figure 3: Pulse Waveform

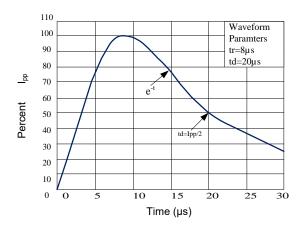


Figure 4: Clamping Voltage vs. Peak Pulse Current

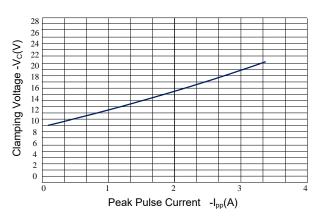


Figure 5: Capacitance vs. Reverse Voltage

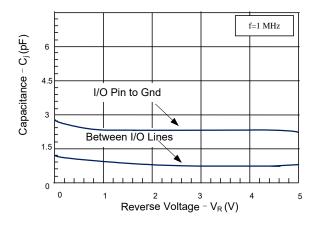
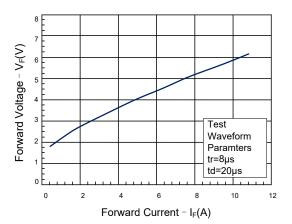


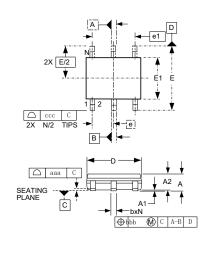
Figure 6: Forward Voltage vs. Forward Current

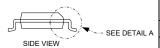


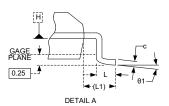


Outline Drawing - SOT-23-6L

PACKAGE OUTLINE

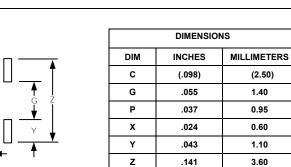






NOTES:

- 1. Controlling Dimensions are In Millimeters (Angles In Degrees).
- 2. Datums -A- And -B- To Be Determined At Datum Plane -H-.
- 3. Dimensions "E1" And "D" Do Not Include Mold Flash, Protrusions Or Gate Burrs.





SOT-23-6L

	DIMENSIONS					
DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
Α	.035	ı	.057	0.90	ı	1.45
A1	.000	-	.006	0.00	-	0.15
A2	.035	.049	.051	0.90	1.25	1.30
b	.010	ı	.020	0.35	ı	0.50
С	.003	1	.007	0.08	ı	0.20
D	.110	.114	.122	2.80	2.90	3.00
E1	.060	.063	.069	1.50	1.625	1.75
Е	.110BSC		2.80 BSC			
е	.037 BSC		0.95 BSC			
e1	.075BSC		1.90 BSC			
L	.013	.018	.024	0.35	0.45	0.60
L1	(.024)		(0.60)			
θ 1	0°	ı	8°	0°	ı	8°
N	6		6			
aaa	.004		0.10			
bbb	.008 0.20					
ccc	.008			0.20		

Notes

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